

L Number	Hits	Search Text	DB	Time stamp
1	1185	257/666.ccls.	USPAT	2002/12/01 02:50
2	2	((("4657137") or ("5472085")).PN.	USPAT	2002/12/01 02:52
3	3	((("4657137") or ("5472085") or	USPAT;	2002/12/01 03:11
		("20010000079")).PN.	US-PGPUB	
4	157	((die\$2 or chip\$2) and substrate) near	USPAT;	2002/12/01 03:15
		(cavity or recess))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	64	((((die\$2 or chip\$2) and substrate) near	USPAT;	2002/12/01 03:24
		(cavity or recess))) and (polyimide or	US-PGPUB;	
		tape)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	5539	(substrate near (polyimide or tape))	USPAT;	2002/12/01 04:53
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
7	796	((substrate near (polyimide or tape))) and	USPAT;	2002/12/01 03:26
		((thin or flexible) near substrate)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
8	385	((substrate near (polyimide or tape)))	USPAT;	2002/12/01 03:27
		and ((thin or flexible) near substrate))	US-PGPUB;	
		and (chip or die)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	0	6284569.URPN.	USPAT	2002/12/01 03:41
10	5539	((substrate near (polyimide or tape)))	USPAT;	2002/12/01 04:07
		and(substrate near (flexible or polyimide	US-PGPUB;	
		or tape))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
11	0	"118" and(substrate near (flexible or	USPAT;	2002/12/01 04:07
		polyimide or tape))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
12	0	6284569.URPN. and(substrate near (flexible	USPAT;	2002/12/01 04:08
		or polyimide or tape))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
13	0	6284569.URPN. and(substrate near (flexible	USPAT;	2002/12/01 04:08
		or polyimide or tape))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	385	((((substrate near (polyimide or tape)))	USPAT;	2002/12/01 04:09
		and ((thin or flexible) near substrate))	US-PGPUB;	
		and (chip or die)) and(substrate near	EPO; JPO;	
		(flexible or polyimide or tape))	DERWENT;	
			IBM_TDB	
15	144660	cavity or recess) and(film or substrate or	USPAT;	2002/12/01 04:11
		polyimide	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
16	2607	(cavity or recess) and(film or substrate	USPAT;	2002/12/01 04:13
		or polyimide) and ((chip or die) near	US-PGPUB;	
		(cavity or recess))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
17	1087	((cavity or recess) and(film or substrate	USPAT;	2002/12/01 04:33
		or polyimide) and ((chip or die) near	US-PGPUB;	
		(cavity or recess))) and (rigid or remove)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	

18	2	6179127.URPN.	USPAT	2002/12/01 04:26
19	23	257/643.ccls. and (carrier or rigid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 04:35
20	23	257/643.ccls. and (carrier or rigid or stiff\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 04:48
21	45	257/643.ccls. and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 04:49
22	259	(substrate near (polyimide or tape or flexible)) and ((rigid ot stiff\$4) with carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 04:55
23	259	(substrate near (polyimide or tape or flexible)) and ((rigid or stiff\$4) with carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 04:55
24	136	((substrate near (polyimide or tape or flexible)) and ((rigid or stiff\$4) with carrier)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 04:57
25	0	6284569.URPN.	USPAT	2002/12/01 05:04
26	0	6284569.URPN.	USPAT	2002/12/01 05:04
27	12	("5023202" "5044912" "5101322" "5173766" "5635671" "5652185" "5854741" "6013947" "6111324" "6125232" "6187654" "6214645").PN.	USPAT	2002/12/01 05:04
28	12	("5023202" "5044912" "5101322" "5173766" "5635671" "5652185" "5854741" "6013947" "6111324" "6125232" "6187654" "6214645").PN.	USPAT	2002/12/01 05:07
29	26	5023202.URPN.	USPAT	2002/12/01 05:07

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1	1185	257/666.ccls.	USPAT	2002/12/01 02:50
2	2	((("4657137") or ("5472085")).PN.	USPAT	2002/12/01 02:52
3	3	((("4657137") or ("5472085") or	USPAT;	2002/12/01 03:11
		("20010000079")).PN.	US-PGPUB	
4	157	((die\$2 or chip\$2) and substrate) near	USPAT;	2002/12/01 03:15
		(cavity or recess))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	64	(((((die\$2 or chip\$2) and substrate) near	USPAT;	2002/12/01 03:24
		(cavity or recess))) and (polyimide or	US-PGPUB;	
		tape)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	5539	(substrate near (polyimide or tape))	USPAT;	2002/12/01 04:53
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
7	796	((substrate near (polyimide or tape))) and	USPAT;	2002/12/01 03:26
		((thin or flexible) near substrate)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
8	385	((substrate near (polyimide or tape)))	USPAT;	2002/12/01 03:27
		and ((thin or flexible) near substrate))	US-PGPUB;	
		and (chip or die)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	0	6284569.URPN.	USPAT	2002/12/01 03:41
10	5539	((substrate near (polyimide or tape)))	USPAT;	2002/12/01 04:07
		and(substrate near (flexible or polyimide	US-PGPUB;	
		or tape))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
11	0	"118" and(substrate near (flexible or	USPAT;	2002/12/01 04:07
		polyimide or tape))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
12	0	6284569.URPN. and(substrate near (flexible	USPAT;	2002/12/01 04:08
		or polyimide or tape))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
13	0	6284569.URPN. and(substrate near (flexible	USPAT;	2002/12/01 04:08
		or polyimide or tape))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	385	(((((substrate near (polyimide or tape)))	USPAT;	2002/12/01 04:09
		and ((thin or flexible) near substrate))	US-PGPUB;	
		and (chip or die)) and(substrate near	EPO; JPO;	
		(flexible or polyimide or tape))	DERWENT;	
			IBM_TDB	
15	144660	cavity or recess) and(film or substrate or	USPAT;	2002/12/01 04:11
		polyimide	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
16	2607	(cavity or recess) and(film or substrate	USPAT;	2002/12/01 04:13
		or polyimide) and ((chip or die) near	US-PGPUB;	
		(cavity or recess))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
17	1087	((cavity or recess) and(film or substrate	USPAT;	2002/12/01 04:33
		or polyimide) and ((chip or die) near	US-PGPUB;	
		(cavity or recess))) and (rigid or remove)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	

18	2	6179127.URPN.	USPAT	2002/12/01 04:26
19	23	257/643.ccls. and (carrier or rigid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 04:35
20	23	257/643.ccls. and (carrier or rigid or stiff\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 04:48
21	45	257/643.ccls. and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 04:49
22	259	(substrate near (polyimide or tape or flexible)) and ((rigid ot stiff\$4) with carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 05:17
23	259	(substrate near (polyimide or tape or flexible)) and ((rigid or stiff\$4) with carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 05:24
24	136	((substrate near (polyimide or tape or flexible)) and ((rigid or stiff\$4) with carrier)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 05:18
25	0	6284569.URPN.	USPAT	2002/12/01 05:04
26	0	6284569.URPN.	USPAT	2002/12/01 05:04
27	12	("5023202" "5044912" "5101322" "5173766" "5635671" "5652185" "5854741" "6013947" "6111324" "6125232" "6187654" "6214645").PN.	USPAT	2002/12/01 05:04
28	12	("5023202" "5044912" "5101322" "5173766" "5635671" "5652185" "5854741" "6013947" "6111324" "6125232" "6187654" "6214645").PN.	USPAT	2002/12/01 05:07
29	26	5023202.URPN.	USPAT	2002/12/01 05:07
30	292	(substrate near (polyimide or tape or flexible)) and chuck	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 05:18
31	145	((substrate near (polyimide or tape or flexible)) and chuck) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 05:18
32	5	(substrate near (polyimide or tape or flexible)) and ((transport or move) with((rigid or stiff\$4) with carrier))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 05:33
33	14	4631897.URPN.	USPAT	2002/12/01 05:28
34	18	((solder adj (resist or mask)) near polyimide) same substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 05:40
35	110	257/671.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/01 05:41